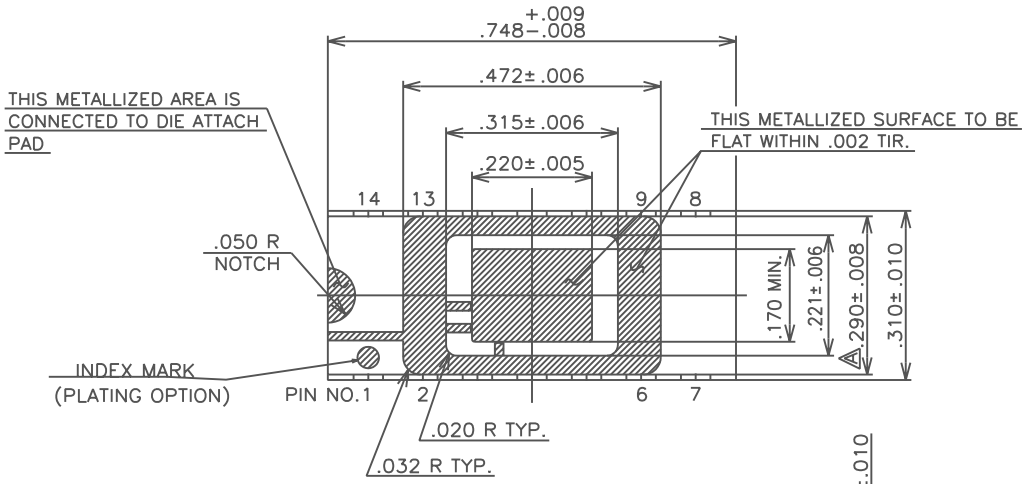

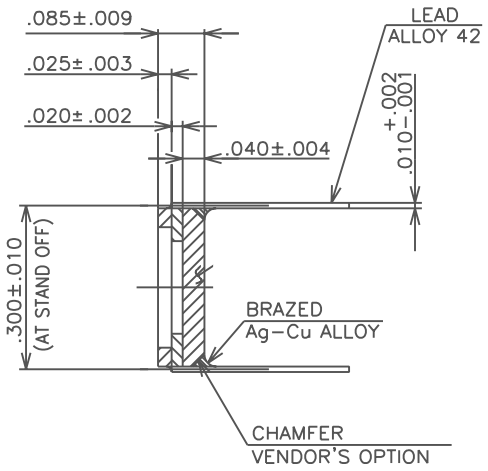

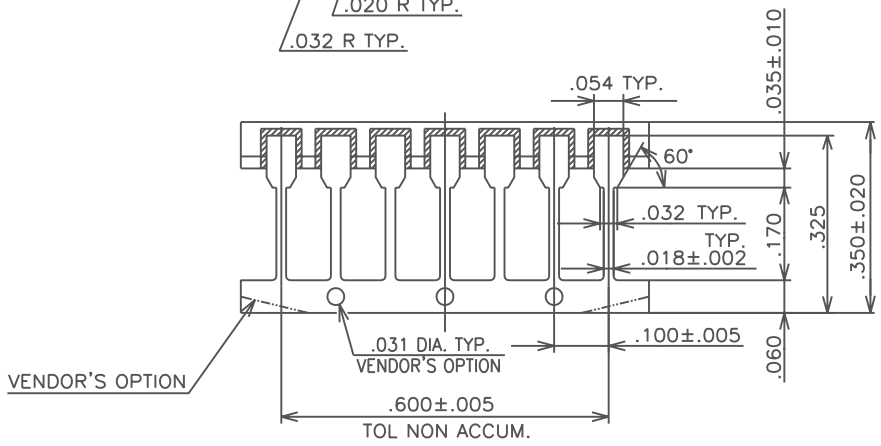

NOTES:

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. LEAD RESISTANCE : 0.2 Ω MAX.
3. SEAL AREA TO BE METALLIZED.
4. DIE ATTACH AREA TO BE METALLIZED.
5. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.

MODIFICATION						
B	CONVERTED CAD DATA , ADDED SHEET 2/2	JAN.31.'00	T.K / M.SU	H.TA / S.K	H.SA	
A	CHANGED : .225→.221	AUG.9.'82	T.H	K.M		
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	

NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
14 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	T.H	K.M		JUL.29.'82
SCALE 5/1	±.005				
MATERIAL AS INDICATED	THIRD ANGLE PROJECTION				
		DRAWING NO.			SHEET 1/2